IN THE CLAIMS:

1. (Previously Presented) A dicing/die bonding sheet adhesively bonded to a semiconductor wafer prior to the dicing of said semiconductor wafer, wherein said dicing/die bonding sheet is provided with a base film, an undercoat layer formed on said base film, and a silicone based adhesive agent layer formed directly on the surface of said undercoat layer and having an adhesive surface adhesively bonded to said semiconductor wafer, wherein said silicone based adhesive agent layer is stripped from said undercoat layer after bonding to said semiconductor wafer.

2. (Cancelled).

3. (Previously Presented) The dicing/die bonding sheet according to claim 1, wherein said undercoat layer is a laminate made up of at least two layers.

4. (Previously Presented) The dicing/die bonding sheet according to claim 1, wherein said base film has a surface area that is not less than said semiconductor wafer.

5. (Previously Presented) The dicing/die bonding sheet according to claim 1, wherein the silicone-based adhesive layer is covered with a strippable protective layer that is stripped prior to bonding said adhesive agent layer to said semiconductor wafer.

6. (Withdrawn) A method of preparing the dicing/die bonding sheet according to claim 1, which includes the step of forming the undercoat layer and the silicone based adhesive agent layer on the base film.

7. (Withdrawn) The method of preparing a dicing/die bonding sheet according to claim 1, which includes the step of forming the silicone based adhesive agent layer and the undercoat layer on a stripping layer, the step of applying the base film to a surface of the undercoat layer, and the step of peeling off the stripping layer.

8. (Withdrawn) The method of preparing a dicing/die bonding sheet according to claim 7, which further includes the step of forming a strippable protective layer on the silicone based adhesive agent layer after the step of peeling off the stripping layer.

9. (Withdrawn) The method of preparing a dicing/die bonding sheet according to claim 5, which includes the step of forming the silicone based adhesive agent layer and the undercoat layer on the strippable protective layer and the step of applying the base film to a surface of the undercoat layer.

10. (Cancelled).

11. (Cancelled).

12. (Previously Presented) The dicing/die bonding sheet according to claim 3, wherein said base film has a surface area that is not less than said semiconductor wafer.

13. (Cancelled).

14. (Cancelled)

15. (Previously Presented) The dicing/die bonding sheet according to claim 3, wherein the silicone-based adhesive layer is covered with a strippable protective layer that is stripped prior to bonding said adhesive agent layer to said semiconductor wafer.

16. (Previously Presented) The dicing/die bonding sheet according to claim 4, wherein the silicone-based adhesive layer is covered with a strippable protective layer that is stripped prior to bonding said adhesive agent layer to said semiconductor wafer.

17. (Cancelled).

18. (Cancelled).

19. (Previously Presented) The dicing/die bonding sheet according to claim 12, wherein the silicone-based adhesive layer is covered with a strippable protective layer that is stripped prior to bonding said adhesive agent layer to said semiconductor wafer.

20. (Cancelled).

21. (Previously Presented) The dicing/die bonding sheet according to claim 1, wherein only said silicone based adhesive agent layer is disposed between said undercoat layer and said semiconductor wafer prior to stripping.

22. (Previously Presented) The dicing/die bonding sheet according to claim 21, wherein only said silicone based adhesive agent layer is bonded to said semiconductor wafer after said silicone based adhesive agent layer is stripped from said undercoat layer.